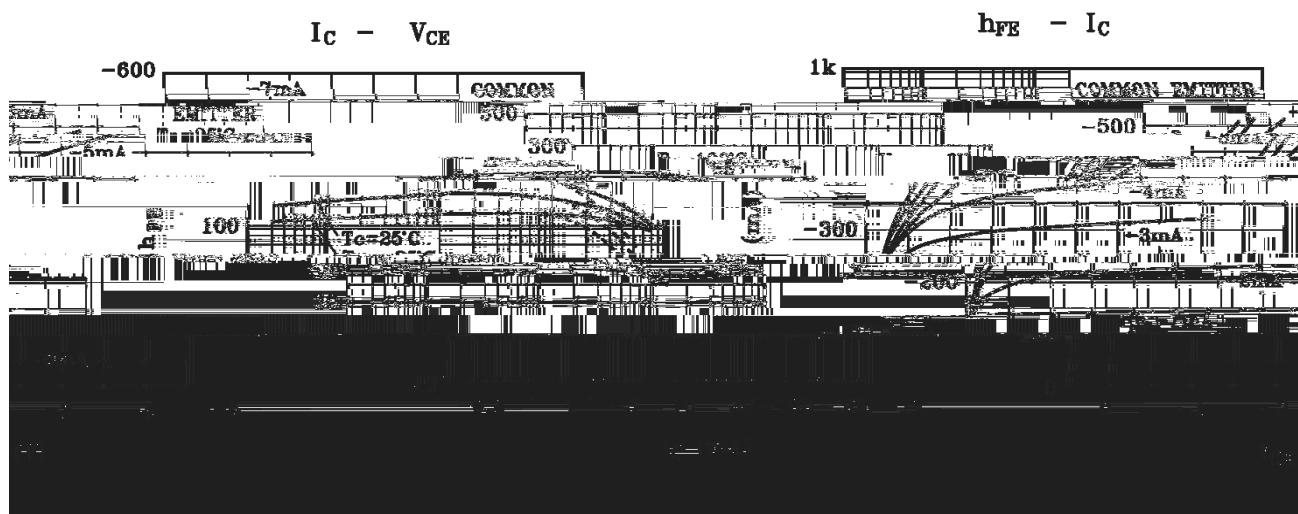
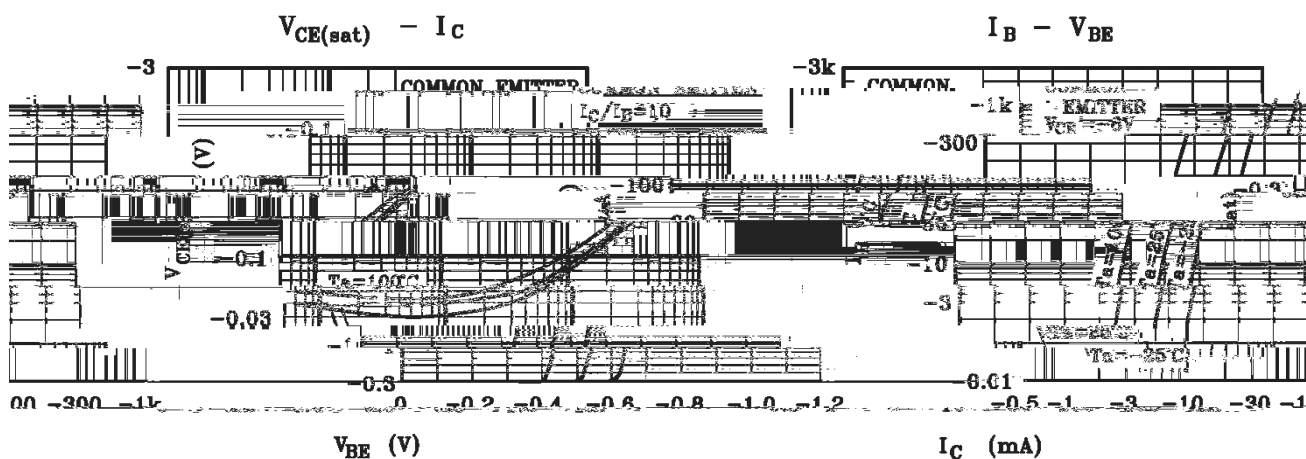
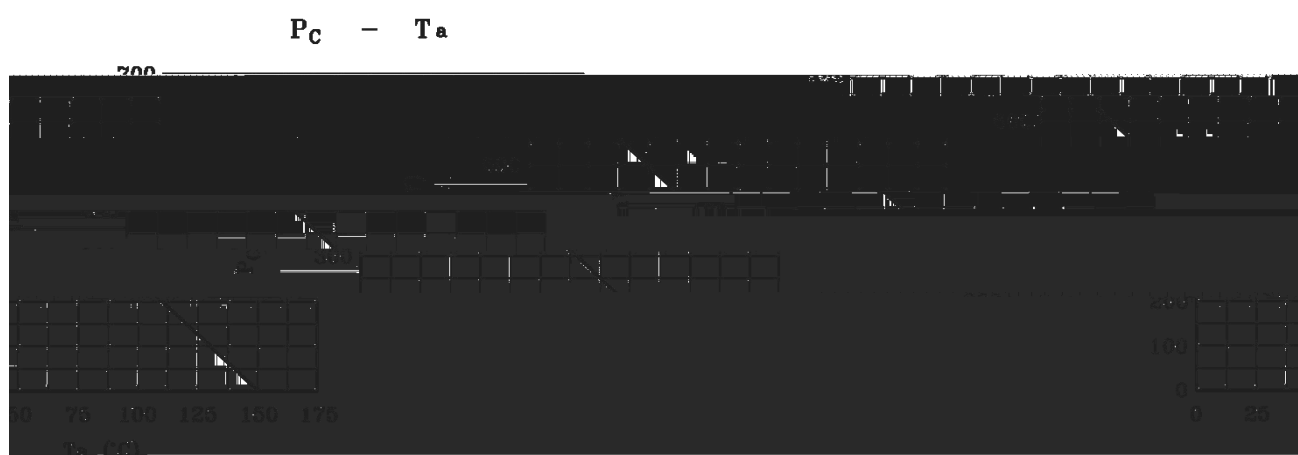


WR0<5 M M E S Q S Æ M y s II 1

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-500	mA

Base Current $-60 \mu A$ at $T_C = 25^\circ C$, $V_{CE} = -50V$, $V_{BE} = -5V$

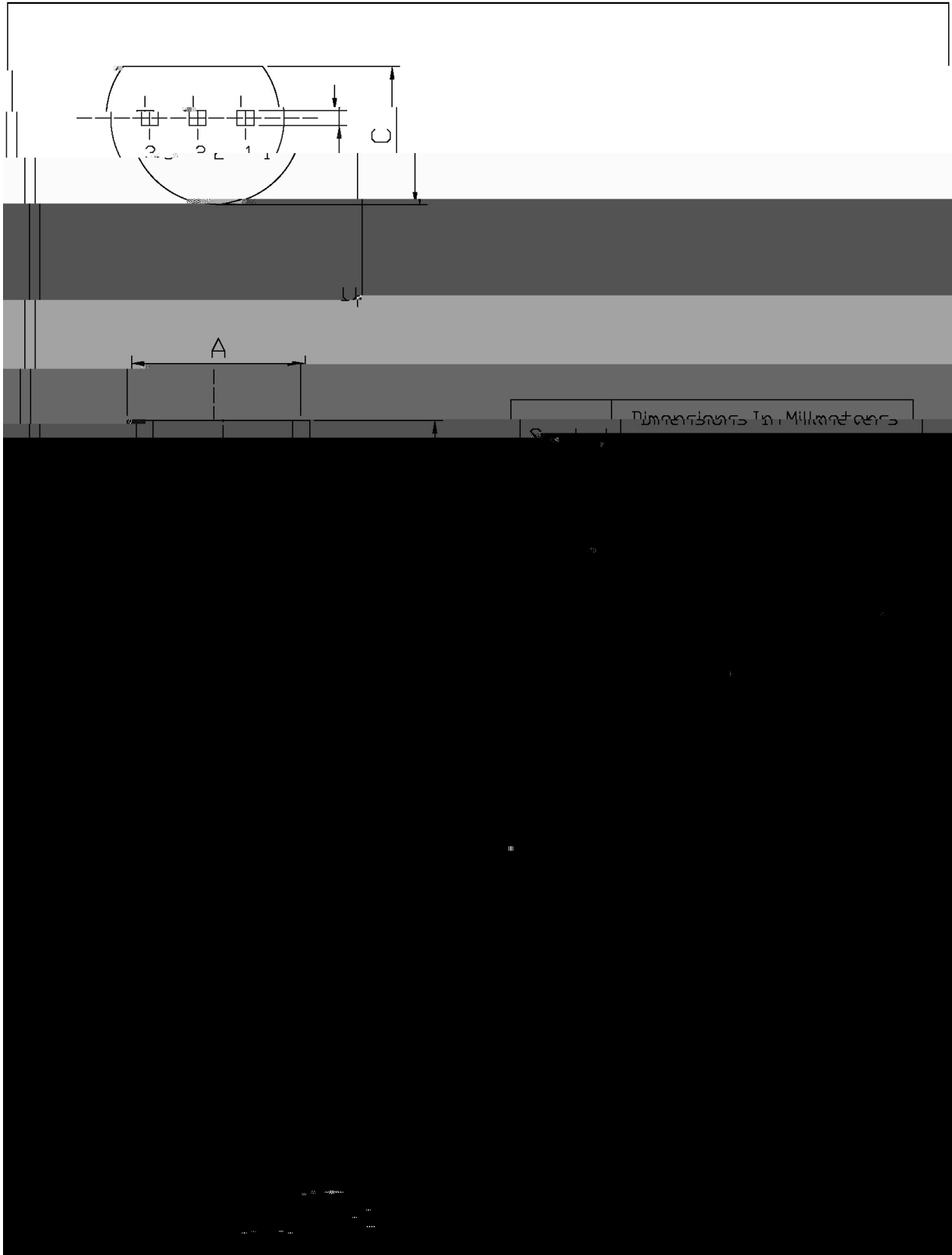
/ Electrical Characteristic Curve



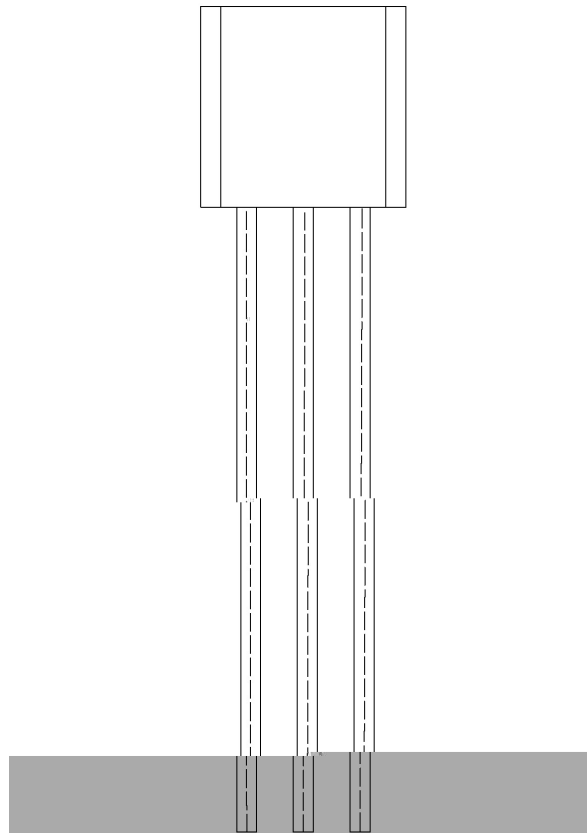
/ Package Dimensions

T0-92

Unit: mm



/ Marking Instructions



б " X

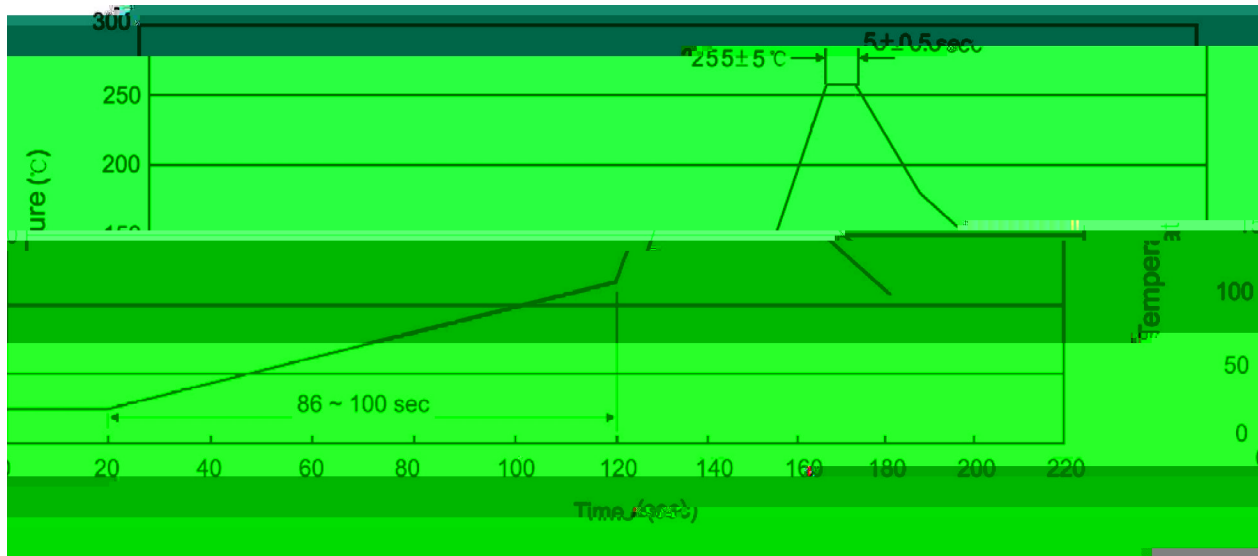
EU:

D533 X

№ 3 " ПД

№ 3 " ПД

() / Temperature Profile for Dip Soldering(Pb-Free)



说明

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

- 1.Preheating:25~150℃, Time:60~90sec.
- 2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 270±5℃ 时间: 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

散装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

纸带 / AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	只纸带	纸带盒	纸带层盒	盒箱	只箱	盒	箱
							小箱 大箱

/ Notices